# 503229577 03/21/2015

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT			
NATURE OF CONVEYANCE:	ASSIGNMENT	ASSIGNMENT		
CONVEYING PARTY DATA				
	Name	Execution Date		
STEVEN HUYNH		11/05/2012		
TSING HSU		11/05/2012		

#### **RECEIVING PARTY DATA**

Name:	ACTIVE-SEMI, INC.	
Street Address: P.O. BOX 957		
Internal Address:	OFFSHORE INCORPORATIONS CENTRE, ROAD TOWN	
City:	TORTOLA	
State/Country:	VIRGIN ISLANDS, BRITISH	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14664850

### **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:		DARIEN K WALLACE		
SIGNATURE:		/Darien K Wallace/		
DATE SIGNED:		03/21/2015		
Total Attachments: 1 source=ACT-043 assignment signed#page1.tif				

#### ASSIGNMENT OF PATENT APPLICATION

WHEREAS, we, Steven Huynh, 1501 Blackfoot Drive, Fremont, CA 94539; and Tsing Hsu, 1433 Rogers Court, Allen, TX 75013 (hereinafter referred to as ASSIGNOR5); having post office addresses that follow our names, are joint inventors of the invention described and claimed in the specification forming part of the United States patent application entitled "POWER MANAGEMENT MULTI-CHIP MODULE WITH SEPARATE HIGH-SIDE DRIVER INTEGRATED CIRCUIT DIE," executed herewith;

WHEREAS, Active-Semi, Inc. (hereafter referred to as ASSIGNEE), a corporation organized under the laws of the British Virgin Islands and having a place of business at P.O. Box 957, Offshore Incorporations Centre, Road Town, Tortola, British Virgin Islands, is desirous of acquiring the entire right, title, and interest in and to the invention and in and to any letters patents that may be granted therefor in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign, and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said invention, said application and any and all letters patents which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty, or otherwise, said invention, application and all letters patents on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors an assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer, and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patents on said invention to ASSIGNEE. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patents on said invention, for litigation regarding said letters patents, or for the purpose of protecting title to said invention or letters patents therefor.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

Inventor's Signature

Steven Huyph Inventor's Printed Name

Inventor's Signature

Tsing Hsu Inventor's Printed Name

Date